

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0602LS	**Issued**	14. May 2021
MA#	MA003684150		
Package	PG-TSDSON-8-26	**Weight***	36.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.71	1.71	17112	17112
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5352	
	non noble metal	copper	7440-50-8	7.988	21.73	22.31	217296	222983
wire	noble metal	gold	7440-57-5	0.028	0.07	0.07	749	749
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1002	
	plastics	epoxy resin	-	1.897	5.16		51610	
	inorganic material	silicondioxide	60676-86-0	16.486	44.84	50.10	448452	501064
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10752	10752
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	553	553
solder	non noble metal	tin	7440-31-5	0.019	0.05		510	
	noble metal	silver	7440-22-4	0.023	0.06		637	
	non noble metal	lead	7439-92-1	0.895	2.43	2.54	24334	25481
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2556	
	non noble metal	copper	7440-50-8	3.816	10.38	10.65	103799	106515
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001			34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2755	
	non noble metal	copper	7440-50-8	4.112	11.19	11.48	111864	114791
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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